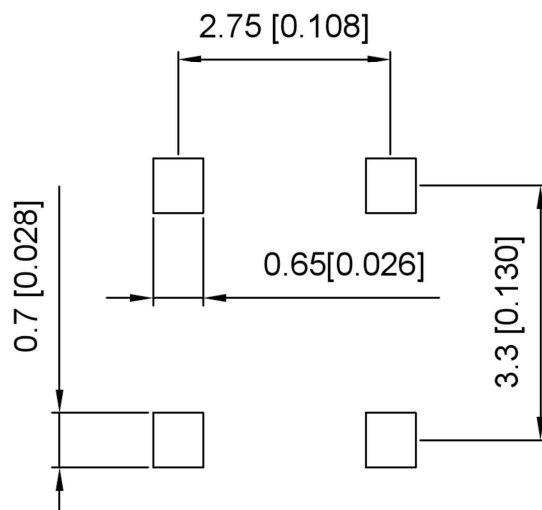
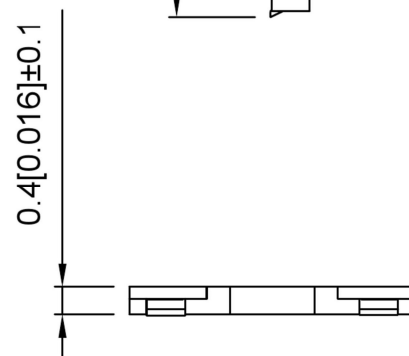
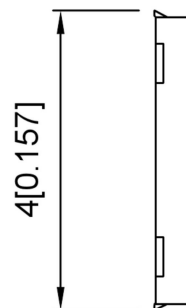
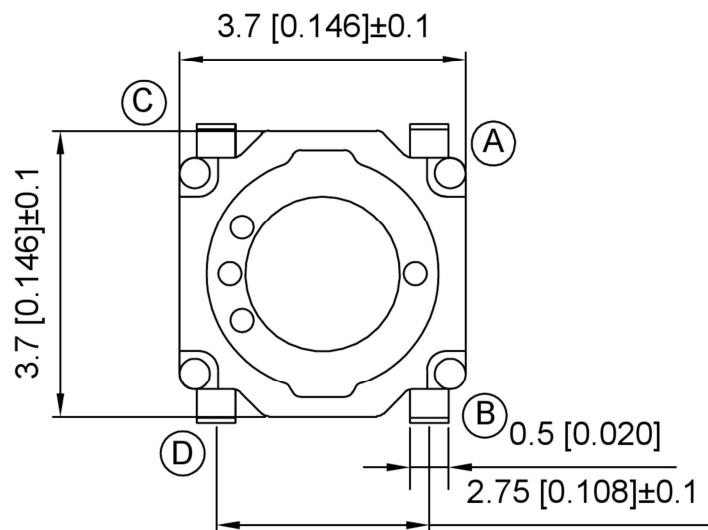
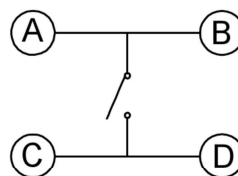




PCB LAYOUT PLAN



CIRCUIT DIAGRAM

SPECIFICATION

Contact Rating:	50mA, 12V DC
Contact Resistance:	100mΩ max
Insulation Resistance:	100mΩ min. 500V DC
Dielectric Strength:	250V AC/1minute
Travel:	0.20mm
Operating Temp:	-30℃~+85℃
Storage Temp:	-30℃~+80℃

PAPT NO	TS-3737-X
Operating Force	B:160gf C:250gf
Height	H:0.4

⑤	Terminal	—	4	Brass (0.30t)	Plating silvering	—
④	Contact	—	1	F.ag/Sus	Natural	—
③	Base	—	1	LCP		—
②	Cover	—	1	Kapton filmPI	Plating Nickel	—
①	Keystake	—	1			—
ITEM	PAPT NAMF	TER,NO	QTY	MATERIAL	FINISHING	REMARK

				ANGLAR	±5°
				L ≤ 4	±0.2
				4 < L ≤ 16	±0.3
				16 < L ≤ 63	±0.4
	DATE	REVISED	APPROVED	L > 63	±0.5
					UNSPECIFIED TOLERANCES
www.alpsr.com www.gdxidz.com www.xbsswitch.com					



DSND		SCALE: N/A	MODEL TYPE:
DWN		VIEW:	TACT SWITCH
CHKD		UNIT: mm/in	PART NO.:
APPD		SIZE: A4	TS-3737-X
			DWG NO.:
			WEIGHT
			SHEET
			REVISIC
			1/1
			A0

DONG GUAN XI BANG ELECTRONIC CO., LTD